

Appin No. 10/713,087
Amdt. Dated September 27, 2004
Response to Office action of July 22, 2004

2

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A support structure for a plurality of printhead modules each having a known coefficient of thermal expansion, the support structure comprising:
an elongated beam formed from two distinct materials, each material provided in segments, the segments of each material alternating along the length of the structure and being bonded to one another end to end, the coefficient of thermal expansion of the beam being substantially equal to the known coefficient of thermal expansion that of the printheads.
2. (Currently Amended) The support structure of claim 1, wherein:
the combined lengths of two adjacent segments between the mounting points of the printhead modules define a pitch and the coefficient of thermal expansion across the each pitch is substantially equal to that of a printhead carried by that pitch.
3. (Original) The support structure of claim 1, wherein:
one material has a coefficient of thermal expansion greater than the other.
4. (Original) The support structure of claim 3, wherein:
the coefficient of thermal expansion of one material is greater than that of silicon and the coefficient of thermal expansion of the other material is less than that of silicon.
5. (Original) The support structure of claim 1, and further comprising:
the combined lengths of two adjacent segments define a beam pitch:
a coefficient of thermal expansion along the beam pitch being substantially equal to that of a printhead carried by that pitch;
there being a plurality of printhead modules are carried by the support structure and being spaced apart by a printhead pitch; and
the beam pitch and printhead pitch are substantially the same.
6. (Original) The support structure of claim 5, wherein:

Appln No. 10/713,087
Amdt. Dated September 27, 2004
Response to Office action of July 22, 2004

3

the printhead modules are all silicon MEMS type modules.

7. (Original) The support structure of claim 6, wherein:
the modules further comprise a silicon substrate in which is formed an array of ink ejector nozzles.
8. (Currently Amended) The support structure of claim 5, wherein:
the coefficient of thermal expansion of ~~a~~the beam pitch is about 2.5×10^{-6} metres per degree Celsius.
9. (Original) The support structure of claim 5, wherein:
the coefficient of thermal expansion of the support structure is about 2.5×10^{-6} metres per degree Celsius.